

**In the Claims**

Kindly amend the claims as shown. Claims remaining in the application are as follows:

1. (Currently Amended): A printed circuit assembly carrier comprising:  
a carrier frame configured to hold a ~~selected~~ printed circuit assembly of at least two  
different printed circuit assemblies assembly types that respectively mount in  
at least two different orientations;  
a first toolless retention feature coupled to a first surface of the carrier frame and  
configured to retain the ~~selected~~ printed circuit assembly of a first printed  
circuit assembly type in a first orientation; and  
a second toolless retention feature coupled to a second surface of the carrier frame  
and configured to retain ~~another the~~ printed circuit assembly in at least one of  
the orientations of a second printed circuit assembly type in a second  
configuration that is different from the first orientation.
2. (Currently Amended): The carrier according to Claim 1 wherein:  
the carrier frame is and first and second toolless retention features are constructed  
from molded plastic and configured to selectively support one of two  
different printed circuit assemblies that install in two different orientations.
3. (Currently Amended): The carrier according to Claim 1 wherein:  
the carrier frame comprises a first member having parallel opposing planar surfaces  
including an interior planar surface and an exterior planar surface, the exterior  
planar surface being the first surface coupled to the first toolless retention  
feature, the interior planar surface being ~~capable of receiving and retaining~~  
the selected configured to receive and retain the printed circuit assembly.
4. (Original): The carrier according to Claim 3 wherein:  
the carrier frame comprises a second member coupled at an end of the first member  
substantially perpendicular to the first member, the second member extending  
beyond the interior planar surface to the second surface that couples to the  
second toolless retention feature.

5. (Currently Amended): The carrier according to Claim 1 ~~wherein further comprising:~~

mounting features coupled to the carrier frame is constructed from plastic; and adapted to mount a selected one printed circuit assembly of the at least two different printed circuit assembly types, whereby the at least two different printed circuit assembly types mount to the same features  
~~the first and second toolless retention features are plastic snaps extending from the carrier frame.~~

6. (Original): The carrier according to Claim 1 further comprising:  
a cable retention feature coupled to the carrier frame.

7. (Currently Amended): An electronic device assembly comprising:  
a housing;  
first and second printed circuit assemblies of respective different first and second types ~~capable of coupling adapted to couple~~ to the housing;  
~~a plurality of first and second~~ identical printed circuit assembly carriers ~~capable of coupling adapted to respectively couple~~ the first and second printed circuit assemblies to the housing, the carriers coupling the printed circuit assemblies of different types to the housing in different orientations via toolless retention features.

8. (Currently Amended): The electronic device assembly according to Claim 7 further comprising:  
a third printed circuit assembly ~~capable of coupling~~ configured to couple to a side of the housing.

9. (Currently Amended): The electronic device assembly according to Claim 7 further comprising:  
a third printed circuit assembly ~~capable of coupling~~ configured to couple to a side of the housing, the third printed circuit assembly being substantially planar and having a first planar side ~~capable of coupling~~ configured to couple to the housing and a second opposing planar side, wherein

~~a the first of the plurality of identical printed circuit assembly carriers couples carrier~~  
coupling the first printed circuit assembly to the second planar side of the  
third printed circuit assembly.

10. (Currently Amended): The electronic device assembly according to Claim 7  
further comprising:

a third printed circuit assembly ~~capable of coupling~~ adapted to couple to a side of the  
housing, the third printed circuit assembly being substantially planar and  
having a first planar side ~~capable of coupling~~ adapted to couple to the housing  
and a second opposing planar side, wherein

~~a the second of the plurality of identical printed circuit assembly carriers couples~~  
carrier coupling the second printed circuit assembly substantially  
perpendicular to the third printed circuit assembly.

11. (Currently Amended): The electronic device assembly according to Claim 10  
wherein:

the second printed circuit assembly and the second of the ~~two~~ identical printed circuit  
assembly ~~carriers~~ carrier are implemented for usage of the electronic device  
assembly in a duplex configuration.

12. (Currently Amended): The electronic device assembly according to Claim 7  
further comprising:

a third printed circuit assembly ~~capable of coupling~~ adapted to couple to a side of the  
housing, wherein:

the electronic device is a hard disk drive;

the housing is a hard disk drive housing, chassis, or cage; and

the first printed circuit assembly is a management printed circuit assembly, the  
second printed circuit assembly is a duplex printed circuit assembly, and the  
third printed circuit assembly is a hard disk drive printed circuit assembly.

13. (Original): The electronic device assembly according to Claim 7 further  
comprising:

a cable retention feature coupled to the carriers.

14-20. (Canceled)

21. (Currently Amended): A printed circuit assembly carrier comprising:  
means for holding a printed circuit assembly, the holding means being ~~capable of~~  
holding adapted to hold a printed circuit assembly of a plurality of different  
printed circuit assemblies assembly types that respectively mount in a  
plurality of different orientations; and  
means for retaining the ~~first~~ printed circuit assembly in an orientation corresponding  
to the printed circuit assembly type using toolless retention.

22. (New): An apparatus adapted for usage in an electronic device comprising:  
a carrier configured to secure a plurality of different printed circuit assembly types;  
a mounting feature coupled to the carrier configured to mount one printed circuit  
assembly of the plurality of different printed circuit assembly types; and  
a plurality of toolless retention features coupled to the carrier and configured to retain  
the mounted printed circuit assembly to the electronic device in an orientation  
relative to the electronic device specific to the mounted printed circuit  
assembly, the plurality of different printed circuit assembly types being  
retained in respective different orientations.

23. (New): The apparatus according to Claim 22 further comprising:  
the carrier configured to secure two different printed circuit assembly types in two  
respective different orientations relative to the electronic device.

24. (New): The apparatus according to Claim 22 further comprising:  
a hard disk drive;  
a hard disk drive housing containing the hard disk drive;  
a hard disk drive printed circuit assembly coupled to the hard disk drive housing;  
a manageability printed circuit assembly; and  
a first carrier coupling the manageability printed circuit assembly to the hard disk  
drive printed circuit assembly in a first orientation.

25. (New): The apparatus according to Claim 24 further comprising:

a duplex printed circuit assembly; and  
a second carrier coupling the duplex printed circuit assembly to the hard disk drive housing in a second orientation.

26. (New): The apparatus according to Claim 22 further comprising:  
a hard disk drive;  
a hard disk drive housing containing the hard disk drive;  
a planar hard disk drive printed circuit assembly having a front side and a rear side,  
the front side being coupled to the hard disk drive housing;  
a manageability printed circuit assembly; and  
a first carrier coupling the manageability printed circuit assembly to the rear side of  
the hard disk drive printed circuit assembly in a first orientation parallel to the  
hard disk drive printed circuit assembly.

27. (New): The apparatus according to Claim 26 further comprising:  
a duplex printed circuit assembly; and  
a second carrier coupling the duplex printed circuit assembly to the hard disk drive housing in a second orientation perpendicular to the hard disk drive printed circuit assembly front side whereby the duplex printed circuit assembly attaches to the hard disk drive printed circuit assembly front side.

28. (New): The apparatus according to Claim 27 wherein:  
the second carrier couples the duplex printed circuit assembly to the hard disk drive housing in physical separation from the hard disk drive housing wherein physical contact is prevented.